

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-10. (Cancelled)

11. A method for processing a lead frame, comprising:

placing a first surface of a lead frame base tape on a first surface of the lead frame;

placing a second surface of the lead frame base tape on a first surface of a porous block;

and

applying a vacuum on a second surface of the porous block, which causes a vacuum to be applied to the second surface of the lead frame base tape.

12. The method, as recited in claim 11, wherein to porous block comprises a plurality of holes on the second side of the porous block, wherein the diameter of each of the plurality of holes is less than 2.00 mm and wherein the vacuum is applied to the second surface of the lead frame base tape through the plurality of holes.

13. The method, as recited in claim 12, further comprising applying chips to a second surface of the lead frame.

14. The method, as recited in claim 13, further comprising heating the porous block.

15. The method, as recited in claim 14, further comprising providing wire bonding between the lead frame and the chips.

16. The method, as recited in claim 15, wherein a density of the plurality of holes is at least 5 holes per square centimeter.
17. The method, as recited in claim 16, wherein the plurality of holes have an area and the second side of the porous block has an area wherein the area of the holes and the area of the second side of the porous block have a ratio, wherein the ratio of the area of the holes to the area of the second side of the porous block is at least 20%.
18. The method, as recited in claim 17, further comprising clamping the lead frame to the second side of the porous block.
19. (Cancelled)